

ELECTRICAL INTERCONNECT ASSEMBLIES AND METHODS OF FORMING
SAME

ABSTRACT

The described embodiments relate to electrical interconnect assemblies (50) and methods of forming same. One exemplary method applies a generally flowable protective material (74) to an electrical interconnect region comprising portions of at least two conductors (54, 58). The method also exposes the protective material (74) to conditions sufficient to render the protective material (74) to a generally non-flowable state which protects the electrical interconnect region from degradation, wherein said exposing also reflows solder (72) positioned proximate the electrical interconnect region to allow the solder (72) to bond with the at least two conductors (54, 58).

(Fig. 1)